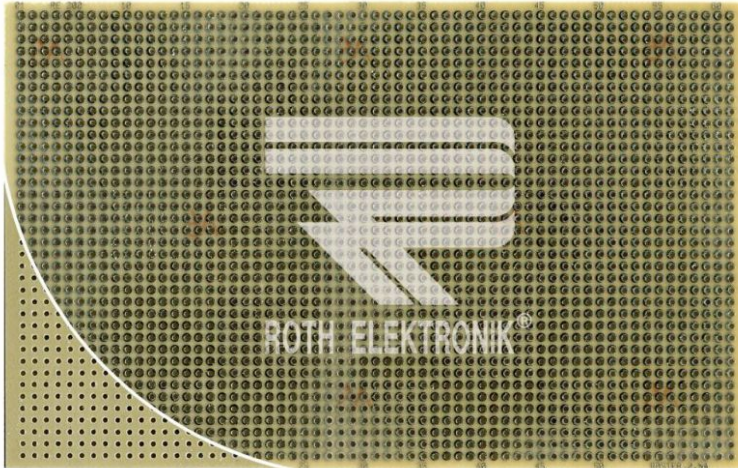


Prototyping Boards Dual Inline



RE200-C3

- CEM3 1.5 mm single-sided 35 µm CU
- hot air leveling (HAL-leadfree)
- 38 x 61 single-hole conductor 2.2 mm Ø
- hole spacing 2.54 x 2.54 mm
- hole dia 1.0 mm
- size 100 x 160 mm